

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Leo M. Higgins III</td> <td>08/30/2012</td> </tr> <tr> <td>Chu-Chung Lee</td> <td>08/29/2012</td> </tr> </tbody> </table>		Name	Execution Date	Leo M. Higgins III	08/30/2012	Chu-Chung Lee	08/29/2012
Name	Execution Date						
Leo M. Higgins III	08/30/2012						
Chu-Chung Lee	08/29/2012						
RECEIVING PARTY DATA							
Name:	Freescall Semiconductor, Inc.						
Street Address:	6501 William Cannon Drive West						
City:	Austin						
State/Country:	TEXAS						
Postal Code:	78735						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13594732</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13594732		
Property Type	Number						
Application Number:	13594732						
CORRESPONDENCE DATA							
Fax Number:	5123457225						
Phone:	512-338-9100						
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>							
Correspondent Name:	HAMILTON & TERRILE, LLP - FREESCALE						
Address Line 1:	P.O. BOX 203518						
Address Line 4:	AUSTIN, TEXAS 78720						
ATTORNEY DOCKET NUMBER:	MT11750TK						
NAME OF SUBMITTER:	Michael Rocco Cannatti						
<p>Total Attachments: 3 source=MT11750TK_Assignment#page1.tif source=MT11750TK_Assignment#page2.tif source=MT11750TK_Assignment#page3.tif</p>							

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **LEO M. HIGGINS, III** and **CHU-CHUNG LEE** have sold, assigned and transferred, and do hereby sell, assign and transfer, unto **FREESCALE SEMICONDUCTOR, INC.**, a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in COPPER BALL BOND FEATURES AND STRUCTURE (Docket No. MT11750TK) described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto **FREESCALE SEMICONDUCTOR, INC.**, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize **FREESCALE SEMICONDUCTOR, INC.**, to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to **FREESCALE SEMICONDUCTOR, INC.**, for the sole use and benefit of **FREESCALE SEMICONDUCTOR, INC.**, its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to **FREESCALE SEMICONDUCTOR, INC.**

We agree that, when requested, we will, without charge to **FREESCALE SEMICONDUCTOR, INC.**, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining

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patents for the inventions in any and all countries and for vesting title thereto in
FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal
representatives or nominees.

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors,
assigns and legal representatives, that the interest and property hereby conveyed is free
from all prior assignment, grant, mortgage, license or other encumbrance.

Leo M. Higgins III DATE: August 30, 2012
LEO M. HIGGINS, III

Trent S. Uehling DATE: August 30, 2012
Signature of First Witness
Name: Trent S. Uehling
Address: 443 Spring Hollow
New Braunfels, Tx 78132

Burton J. Carpenter DATE: August 30, 2012
Signature of Second Witness
Name: Burton J. Carpenter
Address: 1103 Bluff Canyon Dr.
Austin, TX 78754

Chu-Chung Lee
CHU-CHUNG LEE

DATE: 8/29/2012

Brett Wilkerson
Signature of First Witness

DATE: 8/30/2012

Name: Brett Wilkerson

Address: 7102 Dunkirk Dr.
Austin, TX 78736

James Guajardo
Signature of Second Witness

DATE: 08-29-2012

Name: James Guajardo

Address: 101 Parque Court
Georgetown, TX 78626